



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR METAL CAN					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	130	30 000	200 °C + N2	0	0
Solderability	30	90	883 M2003	0	0
Temp. Cycle	628	426 000	-55 °C to 150 °C	0	0